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**PATENT ABSTRACTS OF JAPAN**(21) Application number: **09086147**(51) Int'l. Cl.: **H05K 3/46 H05K 3/24**(22) Application date: **04.04.97**

(30) Priority:	(71) Applicant: <b>HITACHI CHEM CO LTD</b>
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**(54) MANUFACTURE OF  
MULTILAYER PRINTED WIRING  
BOARD****(57) Abstract:**

**PROBLEM TO BE SOLVED:** To provide a method of manufacturing a multilayer printed wiring board excellent in electrical connection.

**SOLUTION:** A hole 4 for the non-through hole for interlayer connection is opened in an insulation glue film 3 comprising a copper foil 1 and a semirigid insulation adhesive layer 2 formed on the roughed face of the foil, the insulation adhesive film 3 with copper foil is superposed on a prepared inner layer circuit board 5 so that the insulation adhesive layer 2 contacts the inner layer circuit board 5, a plastic sheet 6 is superposed during lamination process outside copper foil 1 of the insulation adhesive film 3 with copper foil, integrated into solid body by heat and press, removing the insulation adhesive layer resin 7 extruded out in the hole for the non-through hole 4 by resin etching solution consisting of alkali metal hydroxide, alcohol solvent, and amido solvent, and the inner circuit is electrically connected to the copper foil by plating the inner wall of the hole for the non through hole.

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